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Award

Silicon Wafers for Test Chips

THE OPEN UNIVERSITY

UK6: Contract award notice - Procurement Act 2023 - [view information about notice types](#)

Notice identifier: 2025/S 000-037553

Procurement identifier (OCID): ocds-h6vhtk-055960 ([view related notices](#))

Published 4 July 2025, 4:22pm

Scope

Reference

OUPA11504

Description

As part of the existing Technology Development Element (TDE) contract with the European Space Agency (ESA), the Open University (OU), in company with Teledyne-e2v, are required to procure and test three experimental test chips for characterisation and testing.

Phase 1: To procure Silicon wafers for the manufacture of Front Side Illuminated (FSI) soft X-ray Complementary Metal Oxide Semiconductor (CMOS) imaging detectors to characterise their Electro Optical (EO) performance both pre and post irradiation.

Phase 2: A potential second phase subject to funding to process any remaining Silicon wafers from the first phase for the manufacture of Back Side Illuminated (BSI) soft X-ray CMOS imaging detectors to characterise their EO performance both pre and post irradiation.

Phase 3: A potential third phase subject to funding to procure Silicon wafers to manufacture another batch of either FSI or BSI soft X-ray CMOS imaging detectors for further characterisation of their EO performance both pre and post irradiation.

Cost

Phase 1: £220,000

Phase 2: £250,000

Phase 3: £350,00

Total: £820,000

Contract 1. Silicon Wafers for Test Chips

Supplier

- XFAB

Contract value

- 220000 EUR excluding VAT
- 220000 EUR including VAT

Above the relevant threshold

Award decision date

4 July 2025

Standstill period

- End: 16 July 2025
- 8 working days

Earliest date the contract will be signed

17 July 2025

Contract dates (estimated)

- 18 July 2025 to 31 January 2026
- Possible extension to 1 October 2029
- 4 years, 2 months, 15 days

Description of possible extension:

Extension End Date:

Phase 2: March 2028

Phase 3: September 2029

Main procurement category

Goods

CPV classifications

- 38000000 - Laboratory, optical and precision equipments (excl. glasses)

Contract locations

- UKC - North East (England)
- UKD - North West (England)
- UKE - Yorkshire and the Humber
- UKF - East Midlands (England)
- UKG - West Midlands (England)
- UKH - East of England
- UKI - London
- UKJ - South East (England)
- UKK - South West (England)

Procedure

Procedure type

Direct award

Supplier

XFAB

- Public Procurement Organisation Number: PLGZ-1483-CCTX

1 Silicon Drive, Sama Jaya Free Industrial Zone, Kuching

Sarawak

93350

Malaysia

Email: KCH-Customer-Service-Group@xfab.com

Website: <https://www.xfab.com/>

Small or medium-sized enterprise (SME): No

Voluntary, community or social enterprise (VCSE): No

Supported employment provider: No

Public service mutual: No

Contract 1. Silicon Wafers for Test Chips

Contracting authority

THE OPEN UNIVERSITY

- Charity Commission (England and Wales): RC000391
- Public Procurement Organisation Number: PYNW-6296-ZJQQ

Walton Hall

Milton Keynes

MK7 6AA

United Kingdom

Email: finance-tenders@open.ac.uk

Region: UKJ12 - Milton Keynes

Organisation type: Public authority - sub-central government